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# 9th INTERNATIONAL CONFERENCE IN STRUCTURAL ENGINEERING AND CONSTRUCTION

24 July - 29 July 2017 VALENCIA, SPAIN HOST: Universitat Politècnica de València School of Civil Engineering





# **CALL FOR PAPERS**

#### RESILIENT STRUCTURES AND SUSTAINABLE CONSTRUCTION

The Ninth International Conference in Structural Engineering and Construction (ISEC-9) is aimed at bringing together academics and practitioners. The conference will provide a platform to discuss recent technical advancements and innovations in the profession of structural engineering and construction. It is an excellent opportunity for the exchange of ideas and knowledge, and for discussing future challenges.

#### Who should attend?

Academics, engineers, entrepreneurs, architects, and other interested persons are invited to attend the conference.

### **Call for Papers**

Authors are invited to submit abstracts of between 250 and 400 words at:

https://www.isec-society.org/ISEC-9/abstractsAndPapers/

Authors must create an account, login and upload their abstract. Authors of accepted abstracts will be invited to submit full papers for peer review. One author of each accepted paper will be expected to present the paper at the conference. Accepted papers for which the full registration is paid will be published in the conference proceedings.

#### **Important Dates**

Abstract submission (Final)	15 Nov 2016
Abstract acceptance	9 Dec 2016
Paper submission	14 Jan 2017
Paper review and acceptance	15 Feb 2017
Final paper submission	7 Mar 2017
Registration for Publication in Proceedings	3 April 2017

### **Conference Topics**

The topics to be covered are in all areas of Structural and Construction Engineering, Building Information Models, Air and Water, Architecture and Architectural Engineering, Education and Ethics, Energy, Geotechnical and Foundation Engineering, Risk and Safety Management, Sustainability, and others. Please see details at: https://isec-society.org/ISEC 09/index.php

### **Conference Activity and Dates**

Evening Welcome Reception	24 July 2017
Opening Session	25 July 2017
Conference sessions	25-26 July 2017
Dinner banquet	26 July 2017
Technical tours	27 July 2017
Post-conference cultural tours	28-29 July 2017

### **Conference Venue**

The conference will be held in Valencia, Spain at the Universitat Politècnica de València — School of Civil Engineering

### **About Valencia**

The city of Valencia is the capital of arts and sciences of Spain. It is located near the famous Turia River and is the center of many cultural and art events in Europe. The city offers a wide range of touristic attractions that include visits to the old town Carmen Quarters, medieval fortresses, planetarium, modern arts and science museums, beautiful beaches, and much more.

### Weather

There is a minimal expectation of rain and there is plenty of sunshine. The average daily temperature n Valencia in July is 24°C which can reach an average high of 29°C on the hottest days of the month.

#### Accommodation

Please see details at http://isec-society.org/store/ISEC-9-Accommodations

## **Conference Registration Fees**

	Early Bird Registration	
	Before 3 April 2017	After 3 April 2017
Student	US\$ 875	US\$ 975
Regular	US\$ 975	US\$ 1,075
Student (Developing Country)	US\$ 775	US\$ 875
Regular (Developing Country)	US\$ 875	US\$ 975
Accompanying Person	US\$ 325	US\$ 375
Exhibitor	US\$ 975	US\$ 1,075
Technical Tours	US\$ 35	US\$ 40
Dinner Banquet	US \$75	US \$80
Additional Papers (Beyond 2)	US\$ 250	US\$ 275
Publishing 1 paper without attending	US\$ 375	US\$ 395
Publishing 2 papers without attending	US\$ 475	US\$ 495

Note: fees in brackets are for participants from developing countries

The regular, exhibitor, and student registrations pay only for all conference lunches, coffee breaks, reception, conference proceedings, and technical sessions. Up to two manuscripts are covered by the regular registration fee; each additional manuscript will cost US \$250 EB or \$275 after EB, The accompanying person (AP) registration pays only for all lunches and coffee breaks, reception, and AP tours during the main conference. These shall be an extra charge for all technical tours and post-conference cultural tours.

ICE members will receive a 2% discount on their registration fee.

Please register online at: http://isec-society.org/store/ISEC-9-registration

## Accompanying Person Program

On *July 25 and 26*, accompanying persons (AP registrants) shall have the benefit of participating in tours designed specially for them. This program is only available to AP registrants.

Further information is available at the ISEC-9 website at:

https://isec-society.org/ISEC 09/accompanying.php

#### **Exhibits**

The Conference will provide an opportunity for companies to display their latest products and services in the field of structural engineering and construction. Those interested in having a display booth should contact the local organising committee.

#### **Technical Tours**

More information in due course...

## **Cultural & Networking Tours**

More information in due course...

Cultural and Networking tour registration is extra for all registrants.

More details on the ISEC-9 website at https://isec-society.org/ISEC 09/cultural tours.php

### **Dress Code**

Casual formal wear for it will be Summer in Valencia, Spain during the conference.

Contact Information	ISEC Society
	Email: isec.sec@gmail.com